

THERMALBOARD

**ECONOMICAL & SUSTAINABLE
 RADIANT HEAT PANEL SYSTEM**

JOB:

DESIGNER:

CONTACT:

PRODUCT DESCRIPTION

Thermalboard is a modular radiant panel system constructed from 92% pre-consumer recycled content and meets LEED® v4 Criteria – with zero added formaldehyde and certified grade MR30 moisture resistance. The panels are laminated with aluminum sheeting for maximum conductivity and efficiency. Thermalboard is designed for both new construction and remodeling over a sub-floor or cement. The system includes straight and end combo panels laid out and installed in a pattern. Panels are attached to the subfloor by means of construction adhesive combined with screws, or cross stapling as recommended in the Installation Manual. The pattern creates the pathway into which 3/8” ASTM F 876-877 PEX tubing is placed.

TECHNICAL SPECIFICATIONS

Substrate: High Density MDF. 92% Pre-Consumer Recycled Content. Meets Grade MR30 Moisture Resistance.

Certifications: No Added Formaldehyde (NAF). LEED® v4 Low Emitting Materials Credit Support

Nominal Dimensions: 16” x 48”

Weight: 2.5 lbs / sq. ft. 13.4 lbs / board

Thickness: 5/8”

Typical Board Mix: 62% Straight. 38% Combos.

Surface: .003 Aluminum Laminate

Pallet Size: 4’x4’x32” Full.

PEX: 3/8” Nominal

Pallet Capacity: 99 Boards per Full Pallet.

Groove Depth: 1/2”

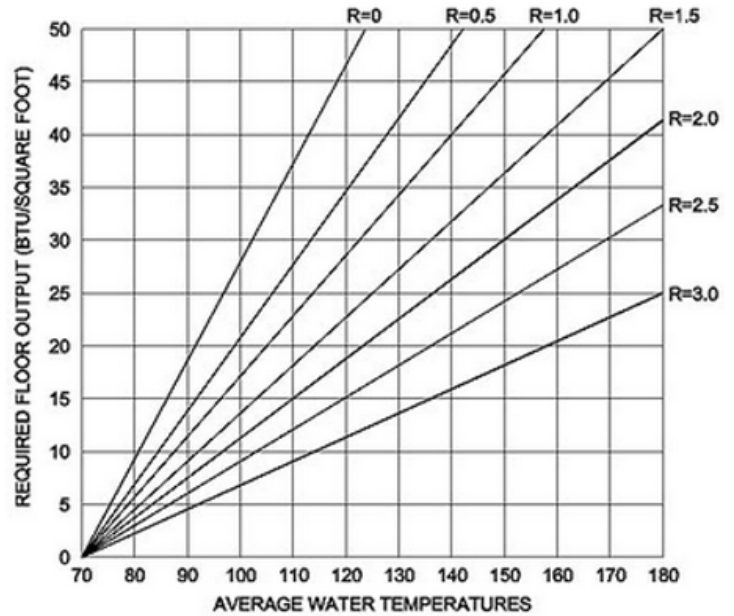
Packaging: Corner Protected. Shrink Wrapped.

PEX Tube Spacing: 8” OC

Green Building: LEED® v4 Low Emitting Materials Credit Support

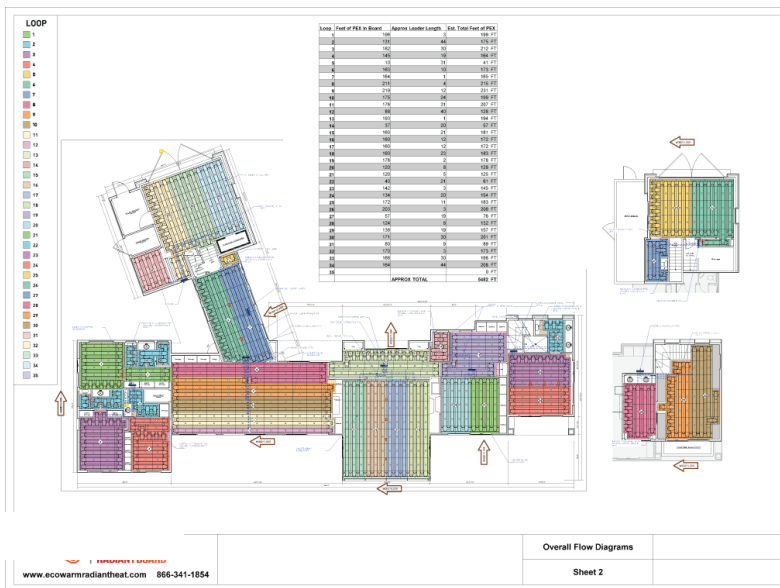
HOW TO USE THE PERFORMANCE CHART

Most manufacturers publish this data or it is available in this format from third-party engineers and manufacturers. The chart demonstrates the supply water temperature required to meet a given heat loss (BTU/Sq/Ft.) with a certain finished floor assembly resistance (R-Value). A low R-value of R=.05 would be tile, while a carpet with a carpet pad might be R=2.5. So for example, start at 20 BTU/Sq/Ft. on the X axis, go over to R=1 (hardwood) and go down and it will read about 105F.



EFFICIENCY CHART

DESIGN & LAYOUT CAD DRAWINGS



STRAIGHT: TBE-S1
VARIABLE: TBE-T1
COMBO: TBE-C1

This Thermalboard project shall be provided detailed project specific CAD drawings and schedules upon acceptance. System shall be installed as described in the current edition of the Thermalboard Installation Manual.